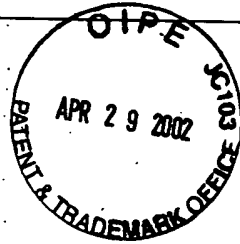


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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COPY OF PAPER



In re Application of:

Hawks, et al.

Serial No.: 09/638,172

Filed: August 11, 2000

For: **Method and Structure for Securing a
Mold Compound to a Printed Circuit
Board**

Art Unit: 2831

Examiner: Hung V. Ngo

AF
2831
#8/C(N6)
Amendments
Y. Robinson
5/7/02

AMENDMENT AND RESPONSE TO FINAL REJECTION

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Honorable Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Dear Sir/Madam:

This is in response to the *final rejection* dated February 1, 2002 in the above-referenced patent application. Please enter and consider the following amendment and remarks.

In the Claims:

Marked up version of twice amended claim 11:

11. (Twice Amended) A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said die, said through hole being filled with a mold compound, said through hole being unplated, said mold compound surrounding and covering said die, wherein said mold compound is locked into said first and second layers of metal of said printed circuit board.

Clean version of twice amended claim 11:

11. A structure comprising:

a printed circuit board including a die attached to a top surface of said printed circuit board;

said printed circuit board comprising a first layer of metal on a bottom surface of said printed circuit board;

said printed circuit board further comprising a second layer of metal on said top surface of said printed circuit board, wherein said second layer of metal is situated below said die;

a through hole traversing said first and second layers of metal of said printed circuit board, said through hole being adjacent to said die, said through hole being filled with a mold compound, said through hole being unplated, said mold compound surrounding and covering said die, wherein said mold compound is locked into said first and second layers of metal of said printed circuit board.